

## NEXX Systems Joins SECAP

**MUNICH--July 1, 2002--**NEXX Systems, a spin-off of ASTeX established in August 2001 and a leading supplier of PVD systems to the advanced packaging industry, has joined the Semiconductor Equipment Consortium for Advanced Packaging (SECAP). With NEXX Systems, under bump metallurgy (UBM) and backside metallization are added to the consortium's equipment portfolio.

"NEXX Systems Nimbus is a unique tool first designed specifically for UBM, backside metallization and high density substrates for the advanced packaging market," commented Dr. Richard Post, CEO of NEXX Systems. "The Nimbus is a mature sputter deposition system, with proven capability and a strong customer base offering the lowest cost of ownership platform, smallest footprint, and elegant simplicity. The product line includes three models capable of handling wafers for 100 mm to 300 mm to meet the requirements of IDMs and foundries."

With NEXX Systems, SECAP closes a technology gap that was opened in November 2001 when the consortium accepted the resignation of Unaxis Semiconductors from SECAP. The SECAP charter states that the consortium will remain neutral to all providers of advanced packaging technologies. The under bump metallization process is necessary in solder bumping, as well as in gold bumping, and provides typically a stack of thin metal films between the bump and the pad that serves as diffusion barrier, wetting layer, and seed layer for electroplating.

SECAP considers NEXX Systems to be the ideal partner to pursue the consortium's goal to support the advanced packaging industry with dedicated process equipment. The SECAP process equipment portfolio now includes wafer plasma cleaning, UBM deposition, resist coating, precision photomasks, exposure and development, UBM spray etching, electroplating, resist stripping and bump inspection. SECAP is the first consortium of this kind established to support the packaging industry. In the next 5 years, the number of wafers that require bumping or redistribution processes is expected to increase by 500 percent. Wafer-level packaging processes will revolutionize the packaging technology and in general will lead to smaller and higher performance devices. Mobile consumer electronics, in particular, will benefit from this industry trend.



## About NEXX Systems

NEXX Systems, a Delaware limited liability corporation, was established in August 2001. NEXX Systems markets and manufactures the Nimbus and Cirrus product lines, which provide process equipment solutions for the advanced packaging and telecommunications industries. NEXX Systems acquired the rights to this technology as part of a definitive purchase agreement with MKS Instruments, Inc., which had acquired the technology as part of the acquisition of ASTeX completed in January 2001. The experienced staff of the ASTeX Systems group joined NEXX Systems and participated in the buy-out. NEXX Systems is currently leasing space within MKS' Wilmington facility to continue uninterrupted service to the company's customer base for these products.

NEXX Systems also offers the Cirrus series, providing unique process capability for the manufacture of opto-electronic devices for telecommunications. New capabilities include process for manufacture active and passive optical devices fabricated from silicon and compound semiconductors. NEXX Systems embodies the entire suite of plasma and reactive gas technology. NEXX Systems plans to apply this technology to future products. For more information, see [www.nexxsystems.com](http://www.nexxsystems.com).

## About SECAP

Established in July 2000, "SECAP" (Semiconductor Equipment Consortium for Advanced Packaging) is a consortium of leading equipment suppliers to the advanced packaging industry. Members of SECAP are Semitool, Suss MicroTec, Image Technology, Matrix Integrated Systems, Electroglas and the Fraunhofer Institute for Reliability and Microintegration (IZM) in Berlin. SECAP addresses challenges in semiconductor packaging, such as the development and validation of process equipment for the industry's conversion to wafer level packaging and 300 mm wafer technology. Within the consortium, the Fraunhofer Institute (IZM) in Berlin acts as a consultant and technical link between the equipment suppliers to identify specific equipment requirements. In addition, the Fraunhofer Institute is the application center for process sequence integration between the different partners' equipment and operates the SECAP process line. The SECAP consortium does not intend to develop and market packaging technologies, since its purpose is not to create a competitive situation with the customers of the equipment companies involved. SECAP aims at supporting the development and successful adaptation of advanced packaging technologies in the semiconductor industry. For more information, see [www.secap.org](http://www.secap.org).